CLAIMS

1. A method for manufacturing a printed wiring board, comprising the steps of: using a carbon dioxide laser to form recess portions such as via holes in a copper clad laminate; plating said copper clad laminate to form interlayer electrical connections forming etching resist layers; and exposing and developing the etching resist layers, thereby effecting a circuit etching treatment, wherein the copper clad laminate is a laminate formed by using waved copper foils to form external copper foils.

2. A method for manufacturing a printed wiring board according to claim 1, wherein each waved copper foil for use in forming the external copper foils of the copper clad laminate includes a bulk copper layer forming a conductor circuit of the printed wiring board, an amount of fine copper particles for ensuring an adhesion strength between the bulk copper layer and a resin substrate, and a rust preventive layer, said bulk copper layer having a thickness of 18 μm or less.

3. A method for manufacturing a printed wiring board according to claim 1, wherein each of the waved copper foils has a surface roughness (Rz) of 2.0 to 20.0 μm.

4. New claim added by Preliminary Amendment.